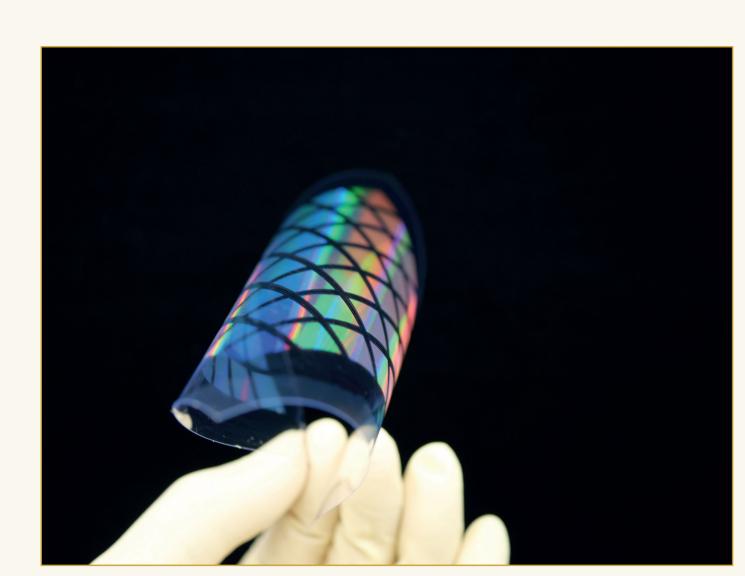
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OrmoStamp®FF

UV-curable Hybrid Polymer for Polymer Working Stamps



Flexible stamp of OrmoStamp®FF on PVC foil (imprint by Profactor GmbH)

Imprinted OrmoStamp®FF on 4" glas wafer.

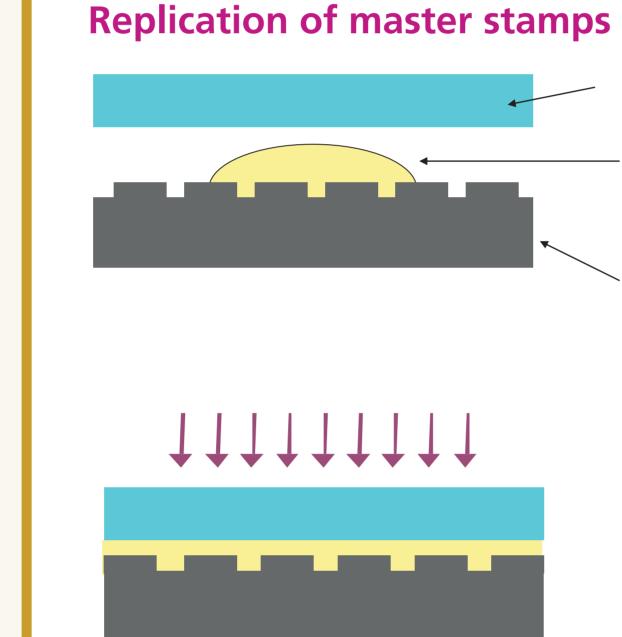
Innovation:

Fluorine-free alternative to established materials.

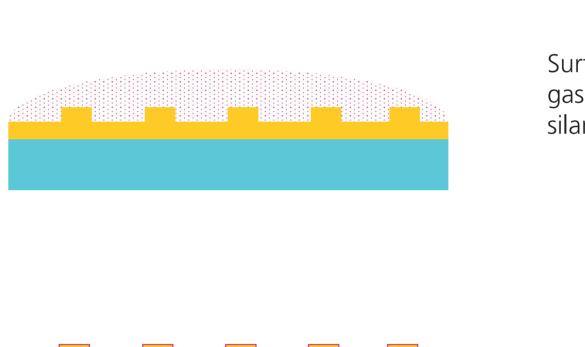


OrmoStamp®FF is a highly transparent material from the hybrid polymer portfolio. This inorganicorganic material provides glass-like transparency in the visible and near-UV. OrmoStamp®FF combines mechanical robustness with flexibility making it an ideal choice as working stamp material. It is suitable as fluorine free hard stamp alternative, for example to quartz, glass or Ni stamps.

Process flow



Anti-sticking layer treatment



Surface treatment, e.g. by gas phase deposition of silane chemistry





OrmoStamp®FF mold, subsequent (optional) hardbake

Pre-treated glass / quartz substrate

dispensing via drop casting or spin

spin-coated with suitable primer

OrmoStamp®FF (liquid resin)

coating (optional pre-bake)

Master stamp (e.g. Si or Ni)

UV exposure and demolding

with anti-sticking layer

Replica of the master stamp with inversed polarity

Unique features:

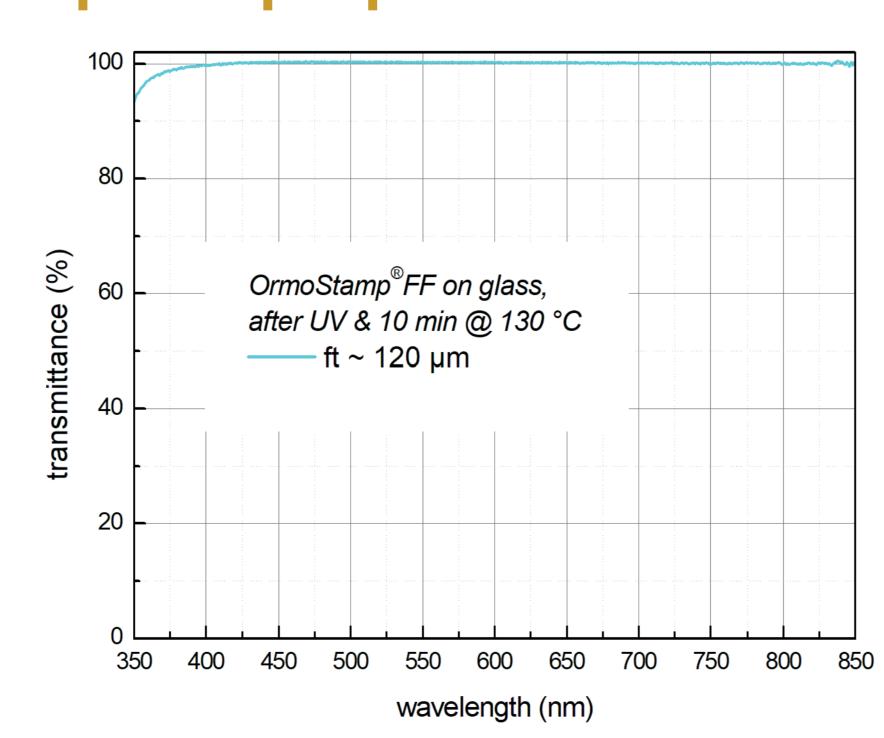
- Solvent-free, ready to use material
- Processing with standard lithography equipment either broadband or LED (365 nm to 405 nm)
- Applicable on flexible (PET, PC, ...) or rigid substrates (Si, glass)
- Silane-based anti-sticking layer treatment is recommended to enhance service life
- Mechanically and thermally stable after UV-curing
- Excellent pattern replication
- Highly transparent for wavelengths from near UV to visible
- Compatible to various resin types

Working stamp from OrmoStamp®FF

Imprinted pillars from OrmoStamp®FF into

OrmoComp®

Optical properties



(Cured material)

Thermal stability	up to 270 °C (short term)
CTE (20-150 °C)	140 ppm K ⁻¹
Shore D Hardness	> 80
Shrinkage (during curing)	~ 6 %
Young's modulus	1.8 GPa